

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JUN BUM KWON	06/26/2014
TEAG SUN JUNG	06/26/2014
SEUNG TAEK BAEK	06/26/2014
WOOK HWA LEE	06/26/2014
YONG HO CHUNG	06/26/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	LSIS CO., LTD.
<b>Street Address:</b>	127, LS-RO, DONGAN-GU
<b>City:</b>	ANYANG-SI, GYEONGGI-DO
<b>State/Country:</b>	REPUBLIC OF KOREA
<b>Postal Code:</b>	431-848
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	14323837
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(213)623-2211
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<b>ATTORNEY DOCKET NUMBER:</b>	2163-3456
<b>NAME OF SUBMITTER:</b>	HARRY S. LEE
<b>SIGNATURE:</b>	/Harry S. Lee/
<b>DATE SIGNED:</b>	07/03/2014
<b>Total Attachments: 1</b>	
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IP-13-0330\_US

Attorney Docket No.

**ASSIGNMENT**

- |                                     |                      |                    |
|-------------------------------------|----------------------|--------------------|
| (1-8) Insert Name(s) of Inventor(s) | (1) KWON, JUN BUM    | (5) CHUNG, YONG HO |
|                                     | (2) JUNG, TEAG SUN   | (6)                |
|                                     | (3) BAEK, SEUNG TAEK | (7)                |
|                                     | (4) LEE, WOOK HWA    | (8)                |

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

- |  |   |
|--|---|
| (9) Insert name of Assignee                    | (9) LSIS CO., LTD.  |
| (10) Insert state of Incorporation of Assignee | (10) Republic of Korea  |
| (11) Insert address of Assignee                | 127, LS-ro, Dongan-gu, Anyang-si, Gyeonggi-do, 431-848, Republic of Korea |

(hereinafter designated as the Assignee) the entire worldwide right, title and interest in the invention known as

- |   |   |
|---|---|
| (12) Insert identification of Invention, such as Title, Case Number or Foreign Application Number | (12) <b>SYNTHETIC TEST CIRCUIT FOR THYRISTOR VALVE IN HVDC TRANSMISSION</b> |
|---|---|

for which the undersigned has (have) executed an application for patent in the United States of America and all patent applications in foreign countries corresponding thereto or based thereon.

1) The undersigned agree(s) to execute all papers necessary in connection with any original, reissue, divisional and continuing United States and foreign applications for the above-identified invention and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.


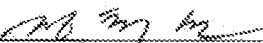
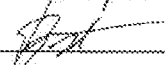
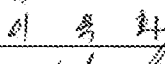
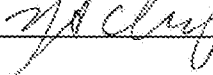
2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

4) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed any agreement in conflict herewith.

The undersigned hereby appoints **the Attorneys associated with Customer No. 35884** the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date: <u>14. 6. 26.</u>	Signature of Inventor (1) KWON, JUN BUM	
Date: <u>14. 6. 26</u>	Signature of Inventor (2) JUNG, TEAG SUN	
Date: <u>14. 6. 26</u>	Signature of Inventor (3) BAEK, SEUNG TAEK	
Date: <u>14. 6. 26</u>	Signature of Inventor (4) LEE, WOOK HWA	
Date: <u>14. 6. 26</u>	Signature of Inventor (5) CHUNG YONG HO	

**PATENT**